Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0212-01** DATE: 12/16/02
Product Affected: Please see attachment for the product list
Date Effective: March 17, 2003

MEANS OF DISTINGUISHING CHANGED DEVICES:
☐ Product Mark
☐ Back Mark
☒ Date Code Prefix (Stepping) change. Please see attachment for details.
☐ Other

Contact: Bimla Paul
Title: Quality Assurance Manager
Phone #: (408)-654-6419
Fax #: (408)-492-8362
E-mail: bimla.paul@idt.com

Attachment:: ☒ Yes ☐ No
Samples: Available upon request.

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☐ Material
☐ Testing
☒ Manufacturing Site
☐ Data Sheet
☐ Other

Selected Logic products will be transferred to IDT's wafer fab facility in Hillsboro, Oregon (Fab 4).
There is no change in die technology.
Please see attachment for the product list and qualification data.

RELIABILITY/QUALIFICATION SUMMARY:

Please see attached Qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ______________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ______________________
E-Mail Address: ______________________
Title: ______________________
Phone# /Fax# : ______________________

CUSTOMER COMMENTS: ______________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY:
DATE:

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ATTACHMENT - PCN #: L0212-01

PCN Type: Fab Site Change

Data Sheet Change: None

Detail of Change: Transfer existing qualified products to Hillsboro, Oregon Wafer Fab Facility (Fab 4).

The following devices are affected by this change. All packages and speed grades are affected.

Part Number	Old Stepping	New Stepping (Fab 4)
IDT74ALVC164245	XE	XE4
IDTQS3126	Y, QA,	X
IDTQS3251	Y	X
IDTQS3390	Y, QA	X
IDTQS32390	Y, QA	Y
IDTQS3244	Z	Y
IDTQS32245	Z	Y
IDTQS32X2245	Z	Y
IDTQS34X2245	Z	Y
IDTQS3L383	Z	Y
IDTQS32XL383	Z	Y
IDTQS4A105	Z	Y
IDTQS4A201	Z	Y

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Qualification Plans: Following reliability tests were performed per Process Family and the qualification results are as follow:

	Required Sample/ # Fails	Lot # 1	Lot # 2
Operating Life Test: Dynamic 1000 hrs @ 125°C or equivalent	116/0	116/0	116/0
Bake & Ball shear Test @ 200°C / 4 ball bonds per device	5/0	5/0	5/0
Temperature Cycling: (-65°C to +150°C, 500 cycles)	45/0	45/0	45/0
HAST: (Biased, 100 Hrs. @ +130°C, +85%RH)	45/0	45/0	45/0
ESD Human Body Model	3/0	3/0	3/0
ESD Charged Device Model	3/0	3/0	3/0
ESD Machine Model	3/0	3/0	3/0
Latch up: (Tested to 1.5X Vcc)	10/0	10/0	10/0

Characterization Data:
Characterization data is available upon request.